

IN THE CLAIMS

Please amend claim 1 as follows:

1. (Five Times Amended) A method of conductively cooling a heat-generating electronic component having an operating temperature range above normal room temperature and a first heat transfer surface disposable in thermal adjacency with a second heat transfer surface of a thermal dissipation member to define an interface therebetween, said method comprising the steps of:

(a) providing a thermally-conductive material which is form-stable at normal room temperature in a first phase and conformable in a flowable second phase to substantially fill said interface, said material having a transition temperature from said first phase to said second phase within the operating temperature range of said electronic component, and said material comprising [a mixture of a resin having a melting temperature of from about 90-100°C, a wax having a melting temperature of from about 50-60°C,] at least one resin or wax component or mixture thereof and at least one thermally-conductive filler;

(b) applying said material in the form of a layer[,] to one of said heat transfer surfaces;

(c) disposing said heat transfer surfaces in thermal adjacency to define said interface; and

(d) energizing said electronic component effective to heat said layer to a temperature which is above said phase transition temperature.

Please amend claim 9 as follows:

9. (Five Times Amended) A thermally-conductive interface for interposition between a heat-generating electronic component having an operating temperature range above normal room temperature and a first heat transfer surface disposable in thermal adjacency with a second heat transfer surface of a thermal dissipation member, said interface comprising a layer of a thermally-conductive material which is form-stable at normal room temperature in a first phase and substantially conformable in a flowable second phase to said interface surfaces, said material having a transition temperature from said first phase to said second phase within the operating temperature range of said electronic component, and said material comprising [a mixture of a

resin having a melting temperature of from about 90-100°C, a wax having a melting temperature of from about 50-60°C,] at least one resin or wax component or mixture thereof and at least one thermally-conductive filler.

Please add the following new claims:

20. The method of claim 1 wherein said material is provided in step (a) as consisting essentially of a blend of:

(i) from about 20 to 80% by weight of a paraffinic wax component having a melting temperature of from about 60-70°C; and

(ii) from about 20 to 80% by weight of one or more thermally-conductive fillers.

21. The interface of claim 9 wherein said material consisting essentially of a blend of:

(a) from about 20 to 80% by weight of a paraffinic wax component having a melting temperature of from about 60-70°C; and

(b) from about 20 to 80% by weight of one or more thermally-conductive fillers.